

Title (en)

ELECTRONIC CIRCUIT BOARD INTERMEDIATE MEMBER, MANUFACTURING METHOD THEREFOR, MANUFACTURING EQUIPMENT THEREFOR, METHOD FOR MANUFACTURING NONCONTACT ID CARD AND THE LIKE, AND EQUIPMENT THEREFOR

Title (de)

ZWISCHENGLIED EINER ELEKTRONISCHEN LEITERPLATTE, HERSTELLUNGSVERFAHREN DAFÜR, HERSTELLUNGSGERÄTE DAFÜR, VERFAHREN ZUR HERSTELLUNG EINER KONTAKTLOSEN ID-KARTE UND DERGLEICHEN UND GERÄTE DAFÜR

Title (fr)

ORGANE INTERMEDIAIRE DE CARTE DE CIRCUIT ELECTRONIQUE; PROCEDE DE FABRICATION; EQUIPEMENT DE FABRICATION; PROCEDE DE FABRICATION D UNE CARTE ID SANS CONTACT ET EQUIPEMENT

Publication

**EP 1699000 A1 20060906 (EN)**

Application

**EP 04807674 A 20041224**

Priority

- JP 2004019317 W 20041224
- JP 2003433502 A 20031226

Abstract (en)

Adverse affects due to a failure interposer board and a blank section are prevented from occurrence by arranging only conforming interposer boards (1) on a carrier tape (2) at every predetermined interval.

IPC 8 full level

**G06K 19/077** (2006.01); **B07C 5/344** (2006.01); **G06K 19/00** (2006.01)

CPC (source: EP KR US)

**G06K 17/00** (2013.01 - KR); **G06K 19/00** (2013.01 - KR); **G06K 19/077** (2013.01 - KR); **G06K 19/07718** (2013.01 - EP US); **G06K 19/07749** (2013.01 - EP US); **G06K 19/07752** (2013.01 - EP US)

Designated contracting state (EPC)

DE

DOCDB simple family (publication)

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DOCDB simple family (application)

**EP 04807674 A 20041224**; CN 200480039086 A 20041224; JP 2004019317 W 20041224; JP 2005517389 A 20041224; KR 20067012794 A 20060626; TW 93140573 A 20041224; US 58289704 A 20041224